

Form \$10-1449 S. Department of Commerce (REV. 28 ADEM) Patent and Trademark Office

Atty. Docket No. Se A110-US 09

Serial No. 09/800,213

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

John H. Coleman

Applicant

(Use several sheets if necessary)

Filing Date March 6, 2001

Group 2826

Exam Init	Document No-						Date	Name	Clas s	Subcla ss	Filing Date if Appropriate	
MLT	5	1	9	8	3	7	1	03-30-93	Li	437	11	
MLT	5	6	3	3	1	7	4	05-27-97	Li	438	475	
MLT	5	0	3	4	3	4	3	07-23-91	Rouse et al.	437	86	
MLT	5	3	7	4	5	6	4	12-20-94	Bruel	437	24	
1LT	5	4	6	1	2	4	5	10-24-95	Gribnikov et al.	257	197	
1LT	6	1	4	4	0	7	2	11-7-00	Iwamatsu et al.	257	347	1-15-99
									/			
	<u> </u>											
								FOREIGN PA	TENT DOCUMENT			
	Document No.							Date	Country	Clas	SubCla ss	<u>Translator</u> Yes No
									/			
								/	<i>1</i>			
•		OTHE	R DC	CUM	ENTS	(in	clu	ding Author	, Title Date, Pertine	nt Pages	Etc.)	<del> </del>
MLT		OTHER DOCUMENTS (including Author, Title Date, Pertinent Pages, Etc.)  Jianming Li et al., Properties of Silicon-on-Defect-Layer Material, in: Materials Research Society Symposium Proceedings Vol. 396, David B. Poker et al., Ed., pp.745-750										
ALT		Jianming Li, New annealing processes and explanation for novel silicon pn junctions formed by proton implantation, Electronics Letters, Vol. 35 (1997), pp. 133-134										

<sup>\*</sup> Examiner: Initial citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

	1 P E		s s	heet <u>2</u> of <u>2</u>			
FOXE PI	10-144 PARENA	U.S. Department of Commerce Patent and Trademark Office	Atty. Docket No. A110-US	Serial No. 09/800,213			
INF	ORMAT	ION DISCLOSURE STATEMENT BY APPLICANT	Applicant John H. Coleman				
(Use	seve	eral sheets if necessary)	Filing Date March 6, 2001	Group 2826			
OTHER DOCUMENTS (including Author, Title Date, Pertinent Pages, Etc.)							
aLT	Jianming Li et al., Properties of proton-implanted p-type Si: supports for the model explaining a novel p-n junction in Si, Nuclear Instruments and Methods in Physics Research B 160 (2000), pp. 190-193						
MLT		J. S. Williams et al., The role of oxygen on the stability of gettering of metals to cavities in silicon, Applied Physics Letters, Vol. 75, No. 16, 18 October 1999, pp. 2424-2426					
VILT		K. Henttinen et al., Mechanicaly induced Si layer transfer in hydrogen- implanted Si wafers, Applied Physics Letters, Vol. 76, No. 17, 24 April 2000, pp. 2370-2372					
MLT		J. Grisolia et al., A transmission electron microscopy quantitative study of the growth kinetics of H platelets in Si, Applied Physics Letters, Vol. 76, No. 7, 14 February 2000, pp. 852-854					

MLI	implanted Si wafers, Applied Physics Letters, Vol. 76, No. 17, 24 April 2000, pp. 2370-2372
MLT	J. Grisolia et al., A transmission electron microscopy quantitative study of the growth kinetics of H platelets in Si, Applied Physics Letters, Vol. 76, No. 7, 14 February 2000, pp. 852-854
MLT	Jianming Li, The new exploration for proton-implanted silicon: the conversion of a surface-region-purification-induced p-n junction into a p-i-n electrical structure approaching silicon on insulator, Semiconductor Sci. Technol. 15 (2000), pp. L6-L9
MLT	J. H. Evans et al., The Annealing of Helium-induced Cavities in Silicon and the Inhibiting Role of Oxygen, Nuclear Instruments and Methods in Physics Research B28 (1987), pp. 360-363
MLT	M. J. Goeckner et al., Plasma doping for shallow junctions, J. Vac. Sci. Technol. B 17(5), Sep/Oct 1999, pp. 2290-2293
MLT	Dixon Tat-Kun Kwok et al., Particle-in-cell and Monte Carlo simulation of the hydrogen plasma immersion ion implantation process, Journal of Applied Physics, Vol. 86, No. 4, 15 August 1999, pp. 1817-1821
Examiner	Minhlan Tran  Date Considered 12/04

<sup>\*</sup> Examiner: Initial citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form 2511/51th 1704/946 communication to applicant.